



王开坤，1968年5月出生，材料科学与工程学院教授，博士生导师。1991年在合肥工业大学锻压工艺及设备专业获学士学位，1994年在合肥工业大学金属材料及热处理专业获硕士学位，2001-2006年亚琛工业大学/北京科技大学联合博士培养并获材料加工专业博士学位。2006-2008年清华大学机械系博士后。主要从事有色金属及颗粒增强复合材料先进制备与半固态成形加工、高性能电子封装材料制备与近净成形技术、微成形技术、高性能板带材成形以及材料成形过程模拟仿真研究。兼任中国国际工程咨询公司咨询专家，全国半固态加工技术学术委员会委员，德国塑性工程学会会员。

【在研科研项目】

1. 国家自然科学基金，半固态灵活触变挤压成形机理及流动前沿质量控制研究（51174028），2012年-2015年
2. 大型企业合作项目，高导热材料制备及性能评估研究（2014-8），2014年-2016年
3. 扬州市工业前瞻性研究计划项目，铝包镁双层复合管半固态共挤压成形工业开发（YZ2014068），2014年-2016年

【代表性学术论文】

1. Kai-kun WANG. Semisolid Forging Electronic Packaging Shell with Silicon Carbon-reinforced Copper Composites [J]. *Rare Metals*, 2013, 32(2): 191-195.
2. Kai-kun WANG, Jin-long FU. A Boubaker Polynomials Expansion Scheme for Solving the Flow of Nonlinear Power-law Fluid in Semi-solid State [J]. *Solid State Phenomena*, 2013, 192-193: 276-280.
3. 王开坤. 铝镁合金半固态成形理论与工艺技术[M]. 北京：机械工业出版社，2012.
4. Kai-kun WANG, Yong-lin KANG, Pu-guang SONG, etc. Preparation of SiCp/A356 Electronic Packaging Materials and Its Thixo-forging [J]. *Transactions of Nonferrous Metals Society of China*, 2010, 20(S3): 988-992.
5. Kai-kun WANG. Thixo-forging and Simulation of Complex Parts of Aluminum Alloy AlSi7Mg [J]. *International Journal of Minerals, Metallurgy and Materials*, 2010, 17(1): 53-57.



Kai-Kun WANG, Prof. Dr.-Ing, received his B.E. and M.E. from Hefei University of Technology in 1991 and 1994 respectively. Directed by Prof. R.Kopp and Prof. G.Hirt, he did his PhD work in IBF at RWTH-Aachen Univ. in Germany. During 2006-2008 he did his post-doctor work in Tsinghua University. In those years, he has put forward many innovative technologies in the area of semi-solid forming, e.g. Thixo-joining, multi-layer tube thixo-co-extrusion, thixo-forming of electronic package shell with composites, flexible-thixo-extrusion, etc. He has published more than 90 scientific papers and got 12 authorized patents in areas of semi-solid forging and extrusion, electronic package shell with composites, etc. He is now the consulting expert of *National Development and Reform Commission*, scientific member of semi-solid forming committee in China, member of plastic forming committee in IBF at RWTH-Aachen University.

【Publications】

1. Kai-kun WANG. Semisolid Forging Electronic Packaging Shell with Silicon Carbon-reinforced Copper Composites [J]. *Rare Metals*, 2013, 32(2): 191-195.
2. Kai-kun WANG, Jin-long FU. A Boubaker Polynomials Expansion Scheme for Solving the Flow of Nonlinear Power-law Fluid in Semi-solid State [J]. *Solid State Phenomena*, 2013, 192-193: 276-280.
3. Kai-kun WANG. Semisolid Forming Theories and Processing Technology for Al-Mg Alloys [M]. *Mechanical Industry Press of China*, 2012.
4. Kai-kun WANG, Yong-lin KANG, Pu-guang SONG, etc. Preparation of SiCp/A356 Electronic Packaging Materials and Its Thixo-forging [J]. *Transactions of Nonferrous Metals Society of China*, 2010, 20(S3): 988-992.
5. Kai-kun WANG. Thixo-forging and Simulation of Complex Parts of Aluminum Alloy AlSi7Mg [J]. *International Journal of Minerals, Metallurgy and Materials*, 2010, 17(1): 53-57.